

ABSTRACT OF SU 1781270

DERWENT- 1994-005184
ACC-NO:

DERWENT- 199401
WEEK:

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TITLE: Composite for more efficient, polishing of silicon sheets - contains silicon di:oxide, ethylene glycol etching agent and poly-methyl-siloxane

INVENTOR: KHOMA, M I; KRAVETS, N M ; SUSHKO, R V

PATENT-ASSIGNEE: AS UKR KALUGA SURFACE CHEM INST[AUKAR]

PRIORITY-DATA: 1990SU-4858366 (May 14, 1990)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
SU 1781270 A1	December 15, 1992	N/A	004	C09G 001/02

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
SU 1781270A1	N/A	1990SU-4858366	May 14, 1990

INT-CL (IPC): C09G001/02

ABSTRACTED-PUB-NO: SU 1781270A

BASIC-ABSTRACT:

Composite comprises (mass%): SiO₂ 2-7; ethylene glycol 1.2-3.0; etching agent (aq. ammonia and KOH) 0.5-1.0; surfactant suspension based on polymethylsiloxane 0.2-0.6; with remainder being water. 1 mass% pyrogenic SiO₂, 0.3 mass% aq. ammonia soln., 0.3 mass% KOH, 1.0 mass% ethylene glycol are stirred together for 10 min. at a rate of 1,400 rev/min. 97.2 mass% deionised water is mixed in for 15 min. Before use 0.2 mass% of the organosilicon additive is mixed in for 5 min.

USE/ADVANTAGE - Composite is used in semiconductor mfr. and to polish Si sheets. Composite increases the polishing rate from 46-60 to 60-70 microns/h and simplifies the washing process. Constant

viscosity with changing temp. is obtd. and the composite is inert and stable at increased temp. during the polishing process. Bul.46/15.12.92

CHOSEN- Dwg.0/0
DRAWING:

TITLE-TERMS: COMPOSITE MORE EFFICIENCY POLISH SILICON SHEET CONTAIN
SILICON DI OXIDE ETHYLENE GLYCOL ETCH AGENT POLY METHYL
SILOXANE

DERWENT-CLASS: A97 G04 L03 U11

CPI-CODES: A06-A00E; A12-A03; G04-B04; L04-B04;

EPI-CODES: U11-C06A1A;

POLYMER-MULTIPUNCH-CODES-AND-KEY-SERIALS:

Key Serials: 0213 0231 1306 2556 2597 2669 2687 3273 3279

Multipunch Codes: 017 04- 05- 229 331 38- 504 512 541 58& 59& 59- 609 623 624 627

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1994-002219

Non-CPI Secondary Accession Numbers: N1994-004193